

SOT1095-1

plastic thermal enhanced ball grid array package; 624 balls;
heatsink, 1 mm pitch, 35 mm x 35 mm x1.75 mm body

19 August 2021

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	HBGA624
Package type industry code	HBGA624
Package style descriptive code	HBGA (thermal enhanced ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	17-11-2008
Manufacturer package code	SOT1095-1

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	34.8	35	35.2	mm
package width	34.8	35	35.2	mm
seated height	2	2.25	2.42	mm
package height	1.6	1.75	1.82	mm
nominal pitch	-	1	-	mm
actual quantity of termination	-	624	-	



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2 Package outline

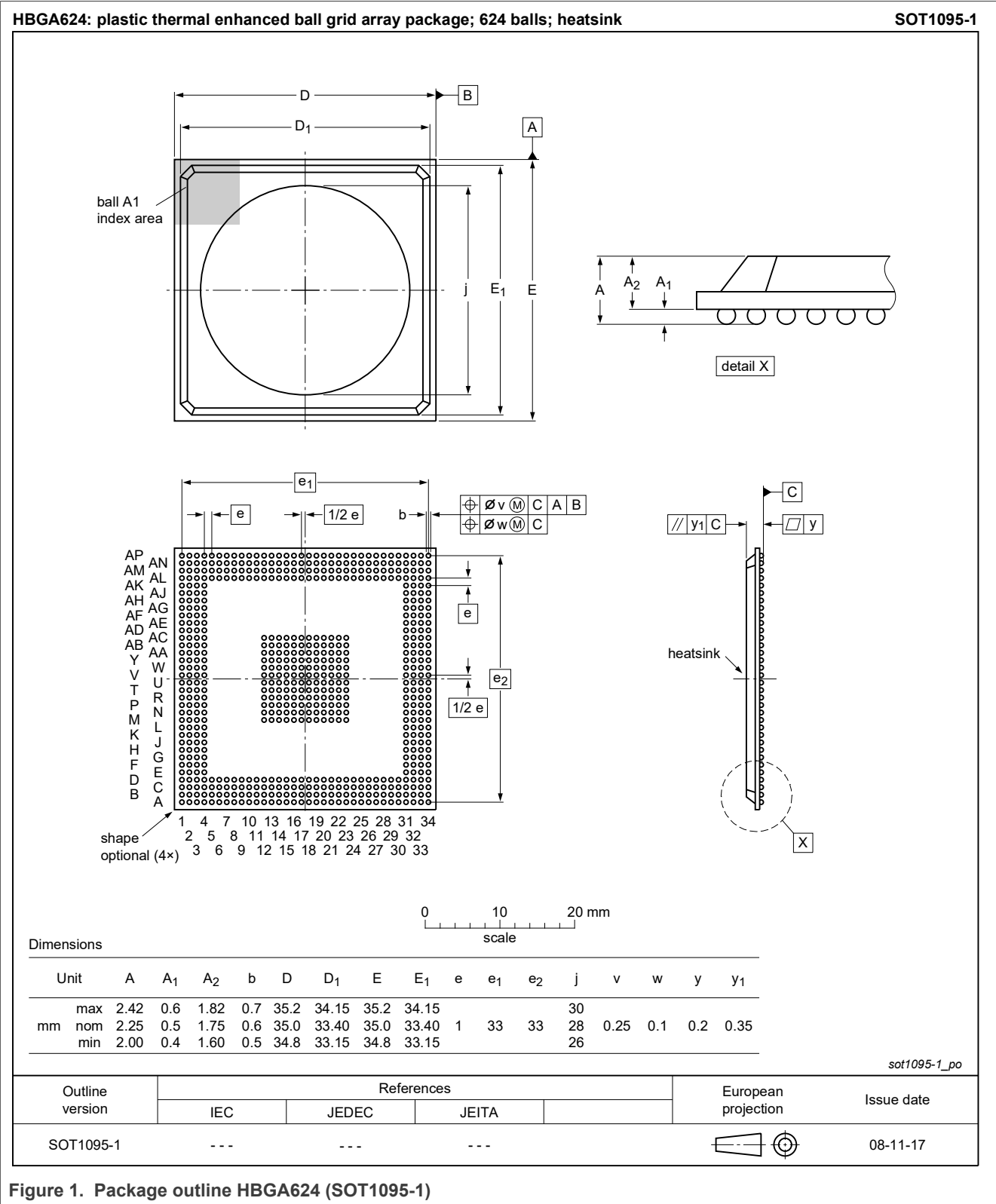


Figure 1. Package outline HBGA624 (SOT1095-1)

3 Legal information

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